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Sohn et al.

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- (54) **SEMICONDUCTOR DEVICE**
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(Continued)

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**

USPC D13/110, 182, 184; 361/713, 728, 736,
361/760, 761, 775, 679.01, 820; 257/666,
257/668, 678, 684, 690; 324/71.5, 252;
174/250, 253; 438/64, 656, 66

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a semiconductor device showing our new design;

FIG. 2 is a front view thereof;

FIG. 3 is a rear view thereof;

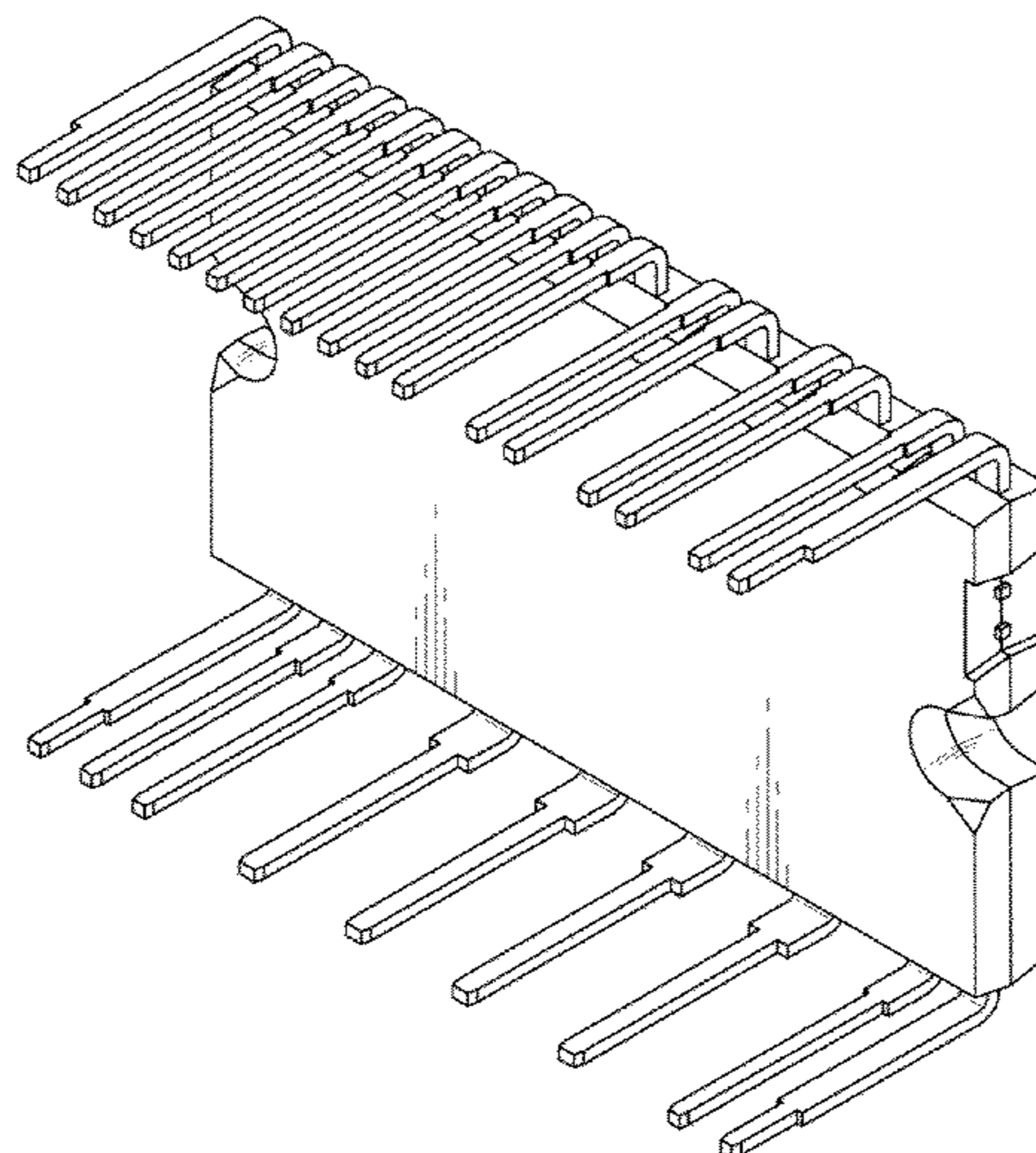
FIG. 4 is a left side view thereof;

FIG. 5 is a right side view thereof;

FIG. 6 is a top plan view thereof; and,

FIG. 7 is a bottom plan view thereof.

1 Claim, 4 Drawing Sheets



(56)

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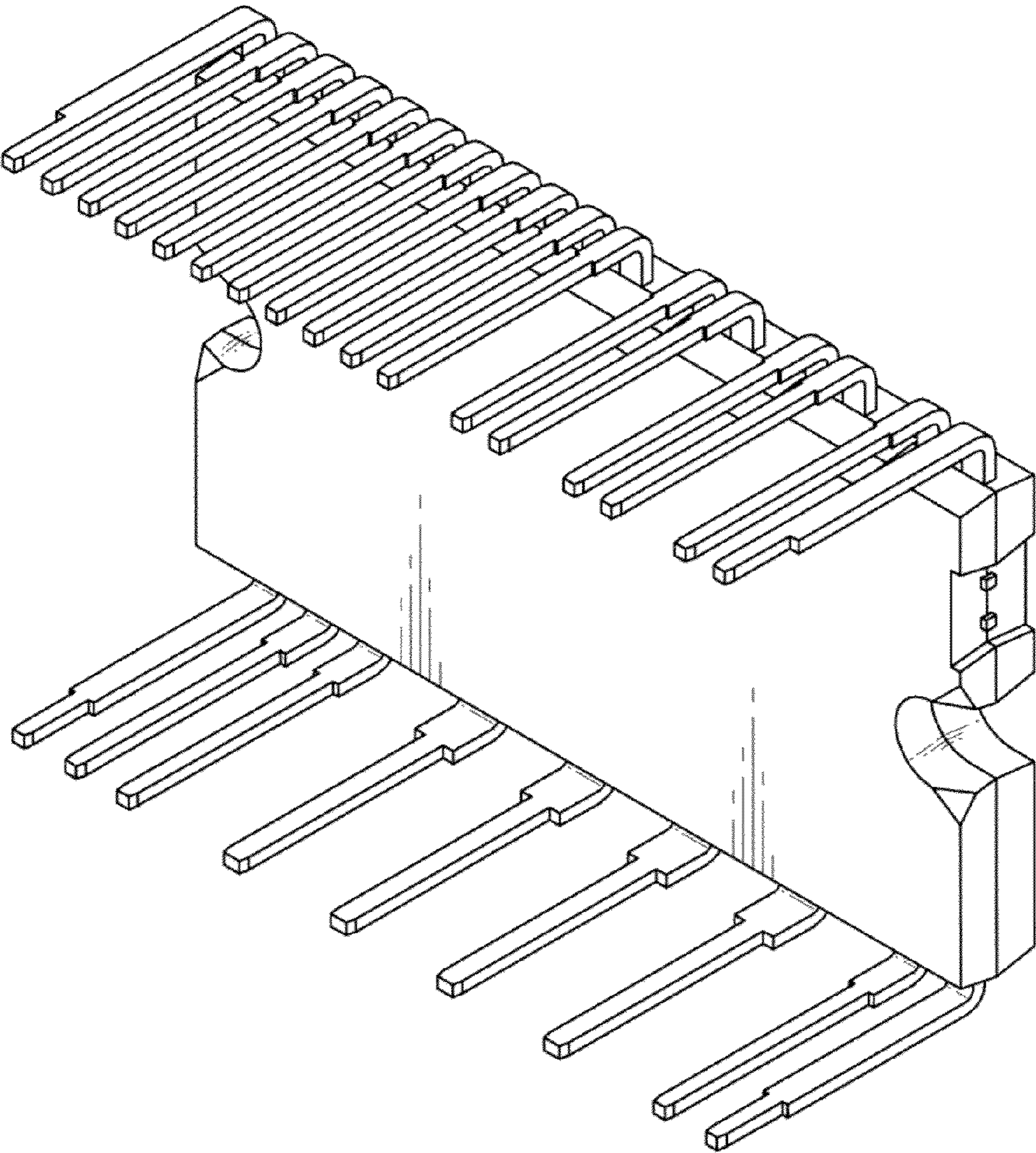


FIG. 1

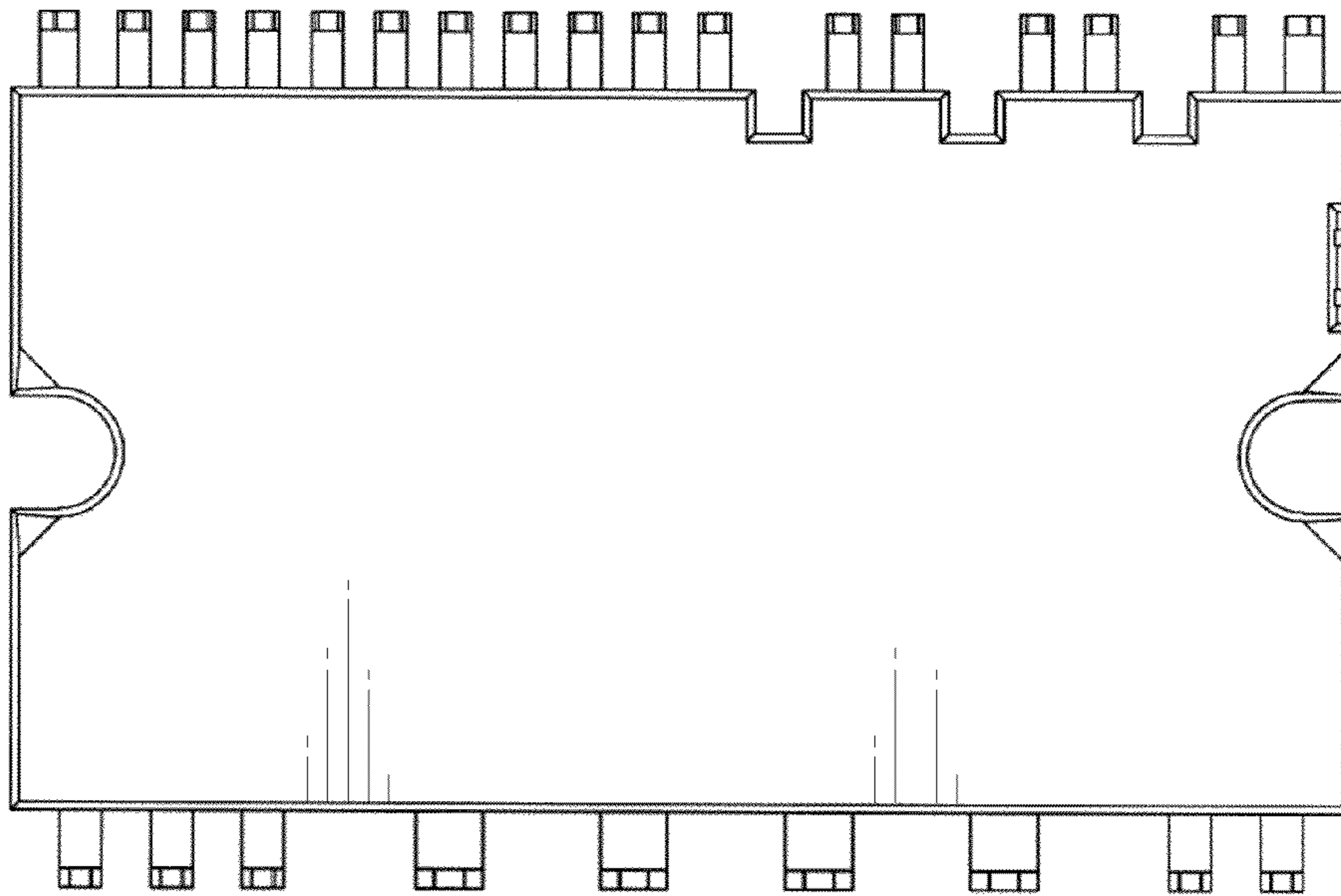


FIG. 2

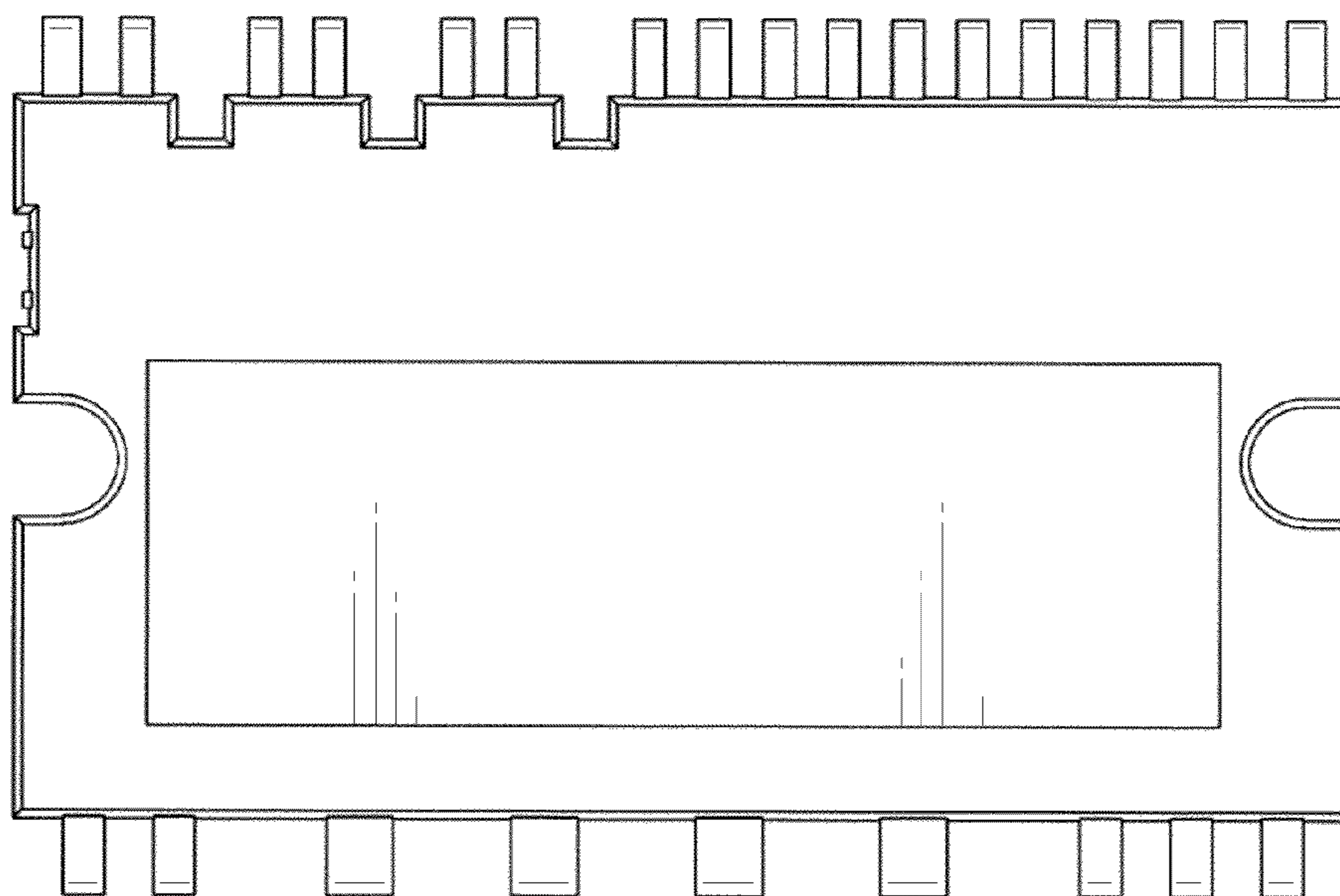


FIG. 3

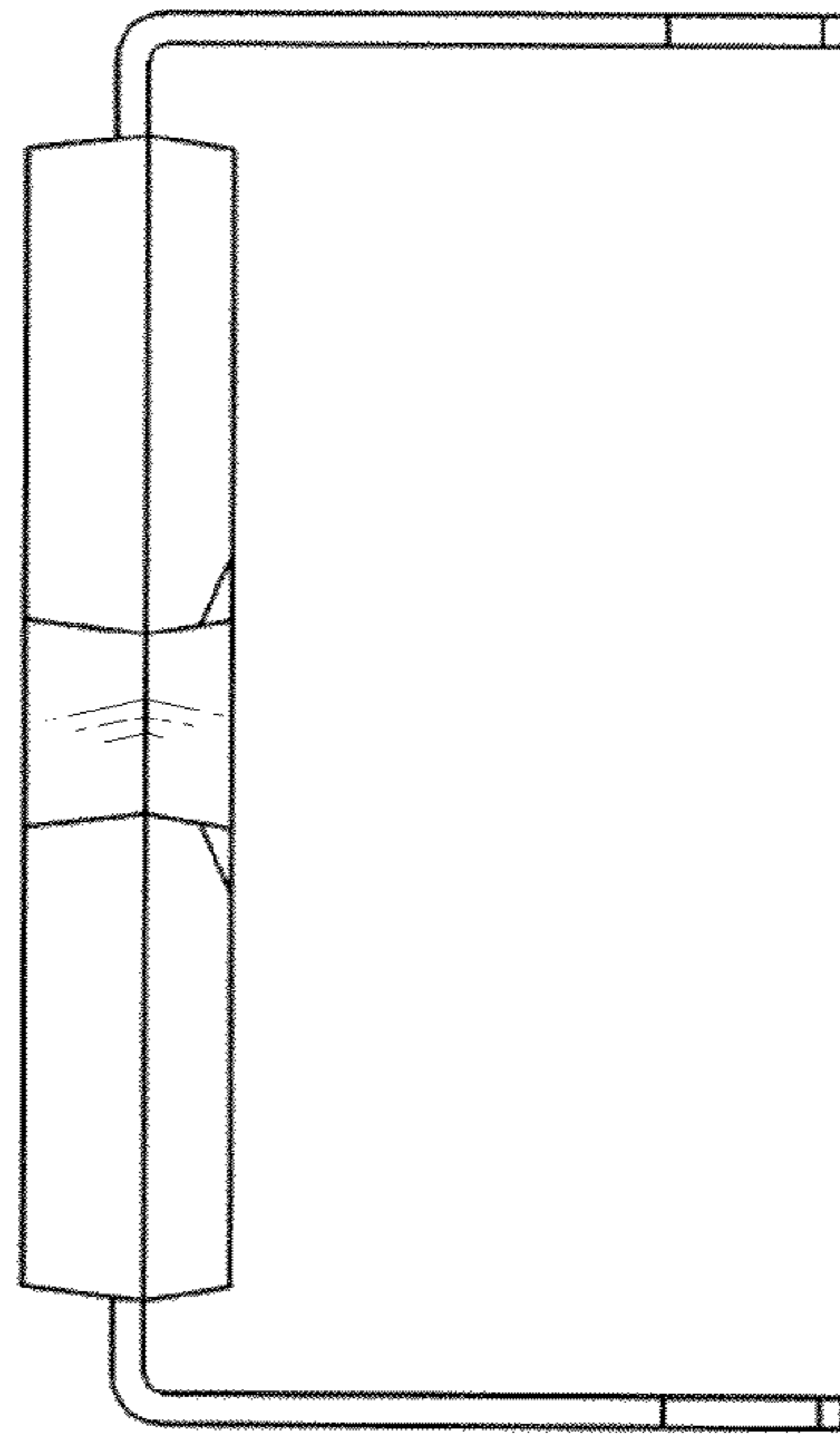


FIG. 4

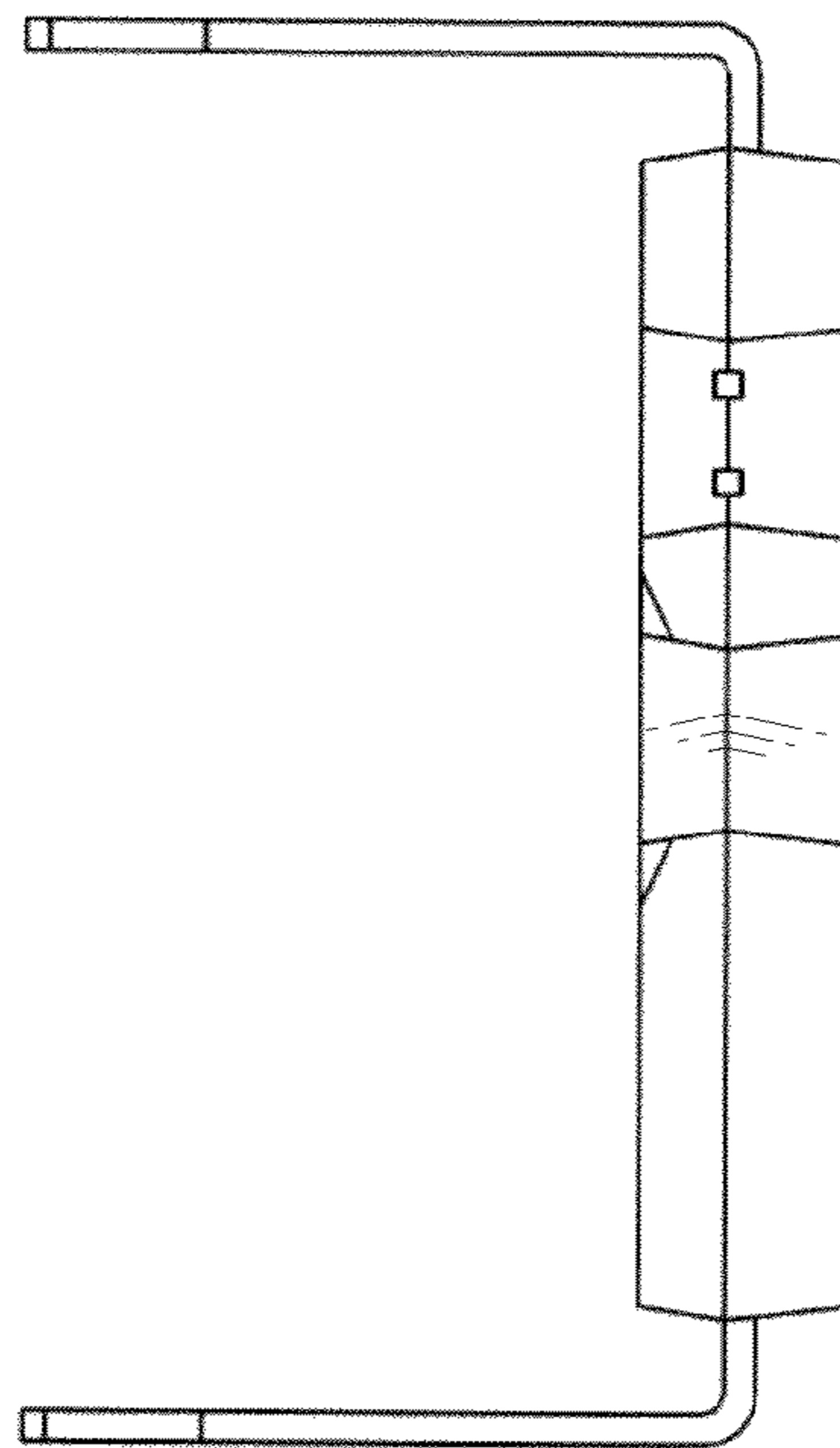


FIG. 5

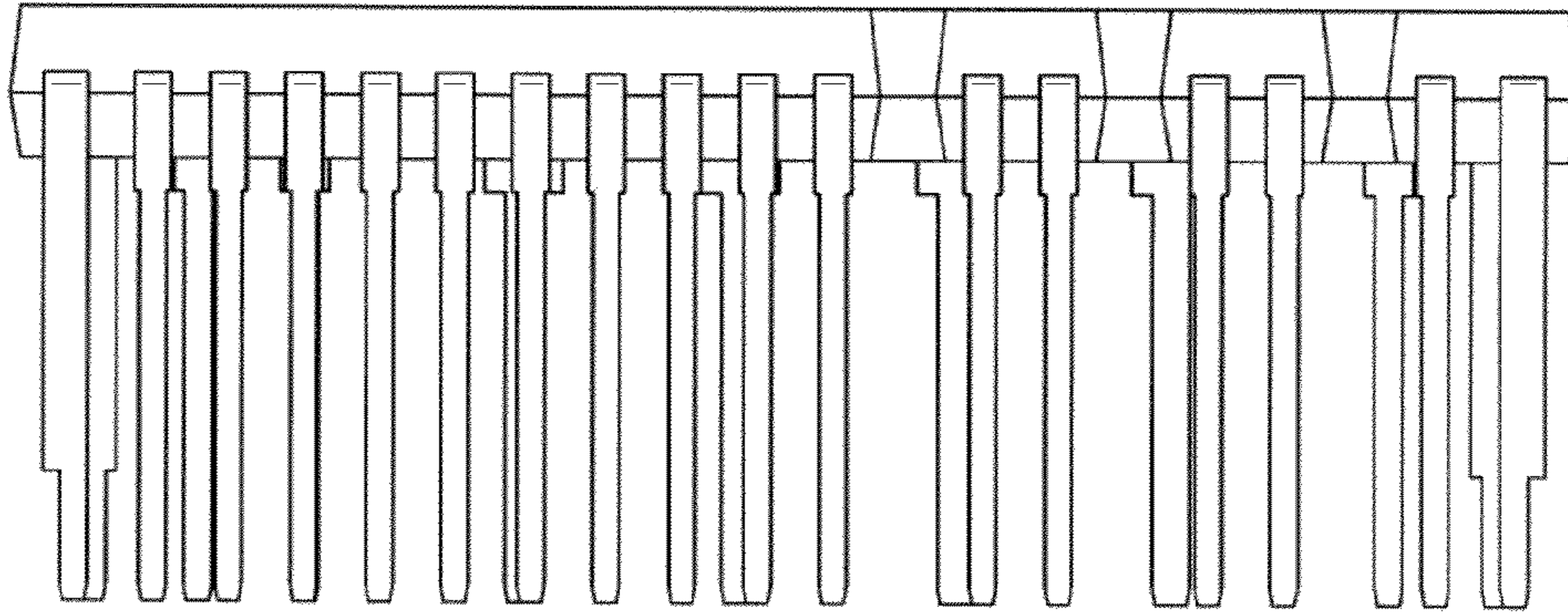


FIG. 6

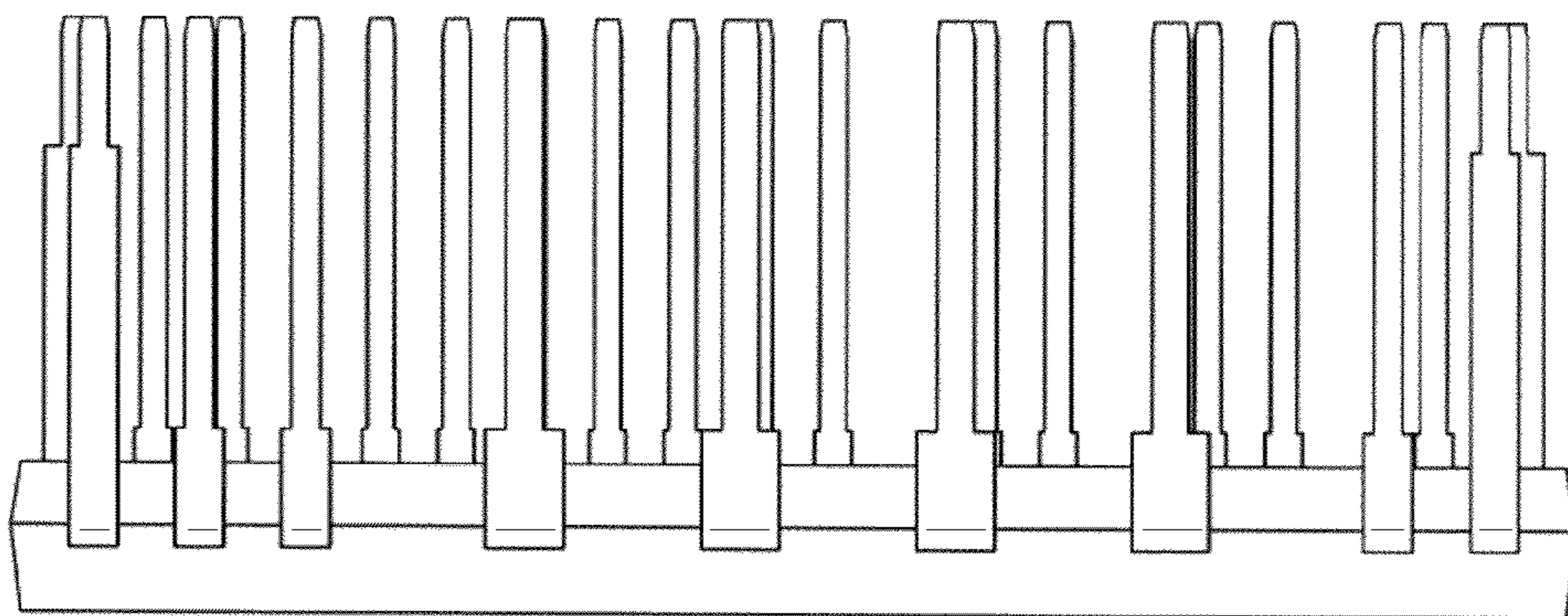


FIG. 7